

ABSTRACT OF THE DISCLOSURE

Compression Molding Method and Compression Mold for Semiconductor Chip

Partition members are provided in predetermined positions on a tip surface of a
5 cavity bottom surface member, to form a plurality of divided cavities in a lower mold
cavity. A height of the partition members is set to be equal to a thickness of divided
resin molded bodies. When sealing semiconductor chips mounted on a substrate into
the plurality of divided resin molded bodies each having a shape corresponding to a
shape of each divided cavity, the cavity bottom surface member is moved upward for a
10 minimum necessary moving distance. As a result, resin in the divided cavities is
pressurized, to form the divided resin molded bodies. Here, grooves to prevent
substrate warp each having a shape corresponding to a shape of each partition member
are formed between adjacent ones of the divided resin molded bodies.

FIGURE 4A